### 650V 4A N-Channel Enhancement Mode Power MOSFET

### **General Description**

BXP4N65 is Bridgelux high voltage MOSFET family based on advanced planar stripe DMOS technology. This advanced MOSFET family has optimized on-state resistance, and also provides superior switching performance and higher avalanche energy strength. This device family is suitable for high efficiency switch mode power supplies.

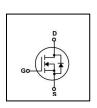
### **FEATURES**

- RDSON $\leq$ 2.8  $\Omega$  @Vgs=10V, Id=2A
- Excellent RDS(ON) and Low Gate Charge

Version: 1.2

- Fast switching capability
- Lead free product is acquired

### **SYMBOL**











TO-251L

TO-252

TO-220

**TO-220F** 

### **ASSEMBLY MESSAGE**

Product Name	Marking	Package	Packaging
BXP4N65U	BXP4N65U	TO-251L	Tube
BXP4N65D	BXP4N65D	TO-252	Tube/Reel
BXP4N65P	BXP4N65P	TO-220	Tube
BXP4N65F	BXP4N65F	TO-220F	Tube

### **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub>=25°C unless otherwise noted)

Parameter		Cumbal	Rating			1114
		Symbol	BXP4N65U/D	BXP4N65P	BXP4N65F	Unit
Drain-Source Voltage		V <sub>DSS</sub>	650			V
Dunin Commant	Continuous (T <sub>C</sub> = 25°C)		4			Α
Drain Current	Continuous (T <sub>C</sub> = 100°C)	- I <sub>D</sub>	2.5			Α
Drain Current	Pulsed (Note1)	I <sub>DM</sub>	16			Α
Gate-Source Voltage		V <sub>GSS</sub>	±30		V	
Avalanche Energy	Single Pulse (Note2)	E <sub>AS</sub>	220		mJ	
	Repetitive (Note1)	E <sub>AR</sub>	15		mJ	
Avalanche Current (Note1)		I <sub>AR</sub>	4		Α	
Peak Diode Recovery dv/dt (Note3)		dv/dt	5		V/ns	
Power Dissipation (Not	e T <sub>C</sub> =25°C	В	77	98	37	W
2)	Derate above 25°C	- P <sub>D</sub>	0.62	0.79	0.3	W/°C
Maximum Junction Temperature		TJ	150			°C
Storage Temperature Range		T <sub>STG</sub>	-55 to 150			°C

Note:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=27.5mH, I<sub>AS</sub>=4.0A, V<sub>DD</sub>=50V, RG=25  $\Omega$ , Starting TJ = 25°C
- 3.  $I_{SD} \le 4.0A$ , di/dt  $\le 300A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting TJ = 25°C

### THERMAL CHARACTERISTICS

Doromotor	Symbol		l lmit		
Parameter		BXP4N65U/D	BXP4N65P	BXP4N65F	Unit
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	1.62	1.27	3.35	°C / W
Thermal Resistance, Junction-to-Ambient R <sub>0JA</sub>		110	62	120	°C/W

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C,unless otherwise Noted)

OFF CHARACTERISTICS         Drain-Source Breakdown Voltage       BV <sub>DSS</sub> Zero Gate Voltage Drain Current       I <sub>DSS</sub> Gate-Body Leakage Current, Forward       I <sub>GSS</sub> Gate-Body Leakage Current, Reverse       △BVDSS         Breakdown Voltage Temperature       △BVDSS         Coefficient       △TJ         ON CHARACTERISTICS         Gate Threshold Voltage       V <sub>GS(TH)</sub> Drain-Source On-State Resistance       R <sub>DS(ON)</sub> Forward Transconductance (Note4)       g <sub>FS</sub> DYNAMIC PARAMETERS         Input Capacitance       C <sub>ISS</sub> Output Capacitance       C <sub>OSS</sub>	VGS=0V, ID=250μA VDS=650V, VGS=0V VDS=520V, TC = 125°C	650			
Zero Gate Voltage Drain Current  Gate-Body Leakage Current, Forward  Gate-Body Leakage Current, Reverse  Breakdown Voltage Temperature  Coefficient  ON CHARACTERISTICS  Gate Threshold Voltage  Drain-Source On-State Resistance  Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Insurance  Insuranc	VDS=650V, VGS=0V	650			
Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Breakdown Voltage Temperature  Coefficient  CON CHARACTERISTICS  Gate Threshold Voltage  Drain-Source On-State Resistance Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Igss  ABVDSS  ACTJ  VGS(TH)  VGS(TH)  GFS  CISS	· ·				V
Gate-Body Leakage Current, Forward Gate-Body Leakage Current, Reverse Breakdown Voltage Temperature  Coefficient  CON CHARACTERISTICS  Gate Threshold Voltage  Drain-Source On-State Resistance Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Igss  ABVDSS  ACTJ  VGS(TH)  VGS(TH)  GFS  CISS	VDS=520V, TC = 125°C	1		1	uA
Gate-Body Leakage Current, Reverse  Breakdown Voltage Temperature  Coefficient  ON CHARACTERISTICS  Gate Threshold Voltage  Drain-Source On-State Resistance  Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Igss  ABVDSS  ACTJ  CHARACTERISTICS  Resistance  Ros(ON)  GFS  CISS				100	uA
Gate-Body Leakage Current, Reverse  Breakdown Voltage Temperature  Coefficient  CON CHARACTERISTICS  Gate Threshold Voltage  Drain-Source On-State Resistance  Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Ciss	VGS=30V			100	nA
Coefficient △TJ  ON CHARACTERISTICS  Gate Threshold Voltage V <sub>GS(TH)</sub> Drain-Source On-State Resistance R <sub>DS(ON)</sub> Forward Transconductance (Note4) g <sub>FS</sub> DYNAMIC PARAMETERS  Input Capacitance C <sub>ISS</sub>	VGS=-30V			-100	nA
ON CHARACTERISTICS  Gate Threshold Voltage VGS(TH)  Drain-Source On-State Resistance RDS(ON)  Forward Transconductance (Note4) gFS  DYNAMIC PARAMETERS  Input Capacitance CISS	S/		0.00		V/°C
Gate Threshold Voltage  Drain-Source On-State Resistance  Forward Transconductance (Note4)  DYNAMIC PARAMETERS  Input Capacitance  Ugs(TH)  RDS(ON)  GFS  Clss	ID = 250 μA		0.62		
Drain-Source On-State Resistance R <sub>DS(ON)</sub> Forward Transconductance (Note4) g <sub>FS</sub> DYNAMIC PARAMETERS  Input Capacitance C <sub>ISS</sub>			•	•	
Forward Transconductance (Note4) g <sub>FS</sub> DYNAMIC PARAMETERS  Input Capacitance C <sub>ISS</sub>	VDS=VGS, ID=250μA	2		4	V
DYNAMIC PARAMETERS Input Capacitance C <sub>ISS</sub>	VGS=10V, ID=2A		2.4	2.8	Ω
Input Capacitance C <sub>ISS</sub>	VDS = 50V, ID = 2A		2.5		S
<u> </u>		•			
Output Capacitance Coss	VD0 05V V00 0V		545		pF
	VDS=25V, VGS=0V, f=1.0MHz		54		pF
Reverse Transfer Capacitance C <sub>RSS</sub>	I-1.UIVITZ		5		pF
SWITCHING PARAMETERS		•			
Turn-ON Delay Time t <sub>D(ON)</sub>	\/DD 205\/ ID 4.4 \/00		11		ns
Turn-ON Rise Time t <sub>R</sub>	VDD=325V, ID=4 A, VGS =		25		ns
Turn-OFF Delay Time t <sub>D(OFF)</sub>	10V ,RG=10Ω		32.5		ns
Turn-OFF Fall-Time t <sub>F</sub>	(Note4,5)		7		ns
Total Gate Charge(Note5) Q <sub>G</sub>	VDS =520V, VGS =10V, ID		13		nC
Gate Source Charge Q <sub>GS</sub>	=4A		3.4		nC
Gate Drain Charge Q <sub>GD</sub>	(Note4,5)		7		nC
SOURCE- DRAIN DIODE RATINGS AND CHA	RACTERISTICS				
Drain-Source Diode Forward Voltage V <sub>SD</sub>	IS=4A, VGS=0V			1.4	V
Diode Continuous Forward Current Is				4	Α
Pulsed Drain-Source Current I <sub>SM</sub>				16	Α
Reverse Recovery Time t <sub>RR</sub>					
Reverse Recovery Charge Q <sub>RR</sub>	VGS = 0 V, ISD = 4A		510		ns

Note: 4. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%

<sup>5.</sup> Essentially independent of operating temperature



### **TYPICAL CHARACTERISTICS**

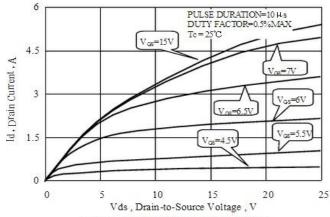


Figure 1. Typical Output Characteristics

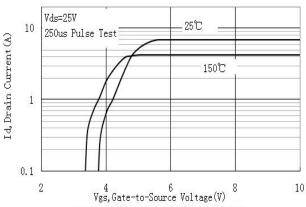


Figure 2. Typical Transfer Characteristics

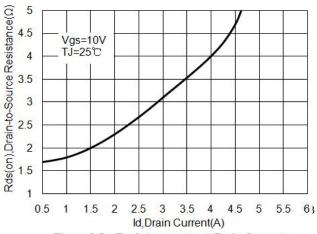


Figure 3.On-Resistance versus Drain Current

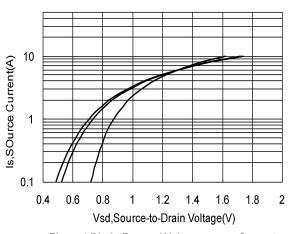


Figure 4.Diode Forward Voltage versus Current

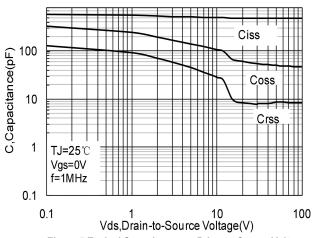


Figure 5. Typical Capacitance vs. Drian-to-Source Voltage

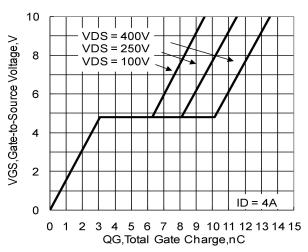


Figure 6. Typical Gate Charge vs. Vgs

### **TYPICAL CHARACTERISTICS(Cont.)**

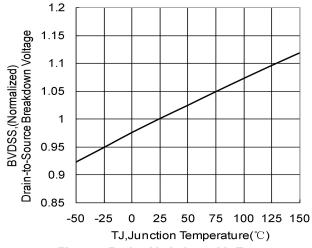


Figure 7.Bvdss Variation with Temperature

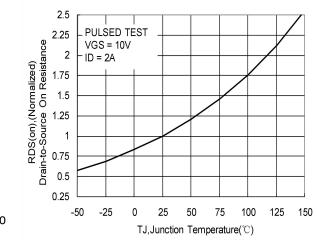
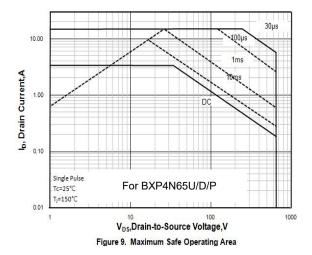
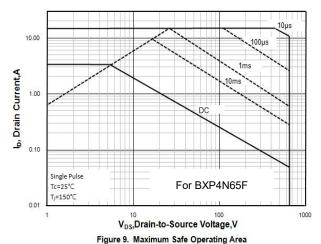


Figure 8.On-Resistance Variation with Temperature



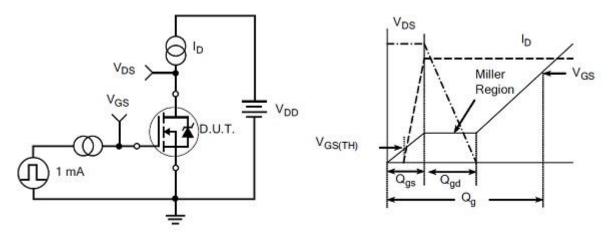
4 3.5 3 ID, Drain Current, A 2.5 2 1.5 1 0.5 0 25 50 75 100 125 150 TC,Case Temperature, °C

Figure 10. Maximum Continuous Drain Current vs Case Temperature



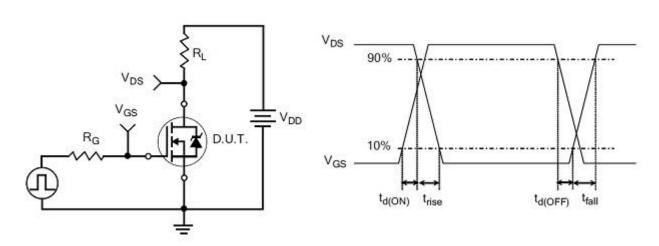
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### **TEST CIRCUITS AND WAVEFORMS**



Gate Charge Test Circuit

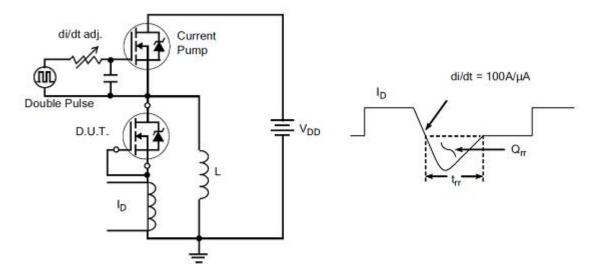
Gate Charge Waveform



Resistive Switching Test Circuit

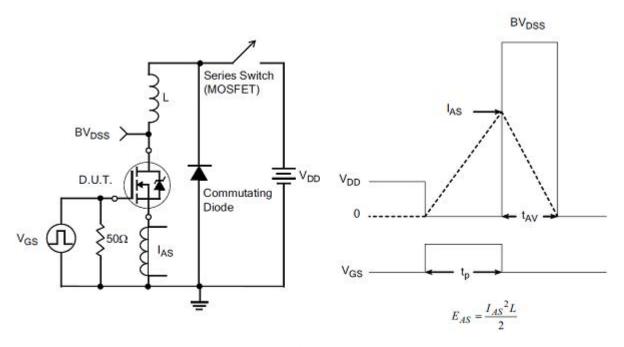
Resistive Switching Waveforms

### **TEST CIRCUITS AND WAVEFORMS(Cont.)**



Diode Reverse Recovery Test Circuit

Diode Reverse Recovery Waveform



Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms



**BXP4N65** 

# **Revision history**

## **Document revision history**

Date	Revision	Changes
15-Oct-2020	1.0	First release
10-Nov-2021	1.1	Update layout format
4-Jan-2022	1.2	Update parameter



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DMN1006UCA6-7 DMN16M9UCA6-7